

## FEATURES

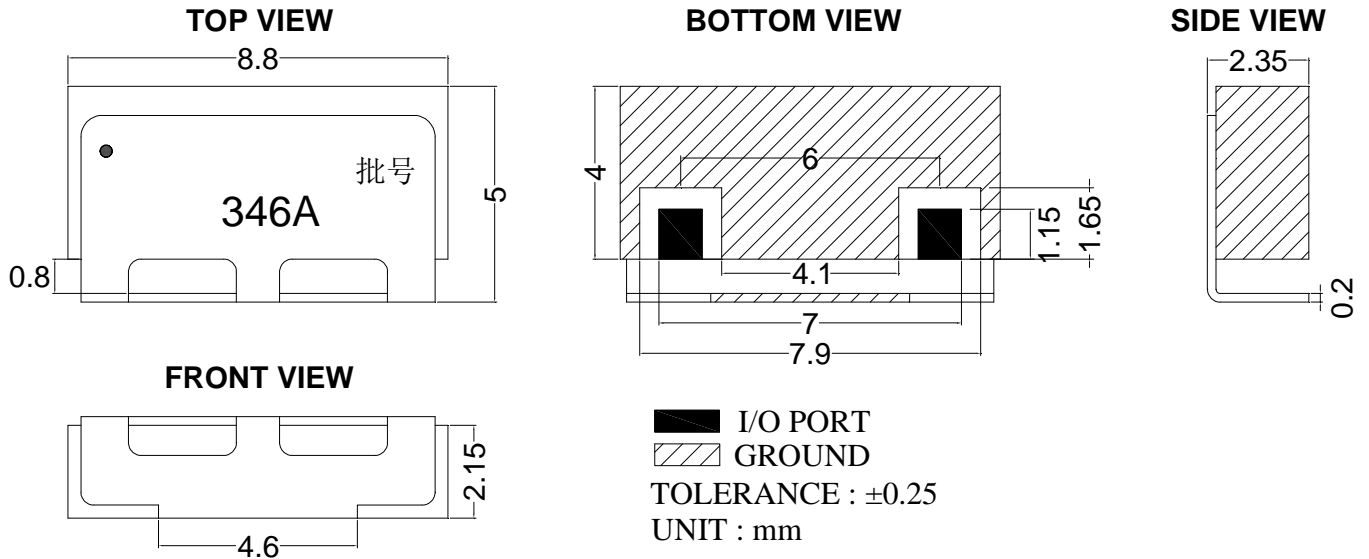
- Small Size,Light weight
- SMT package soldering
- Ideal for Microwave telecommunication

## SPECIFICATIONS

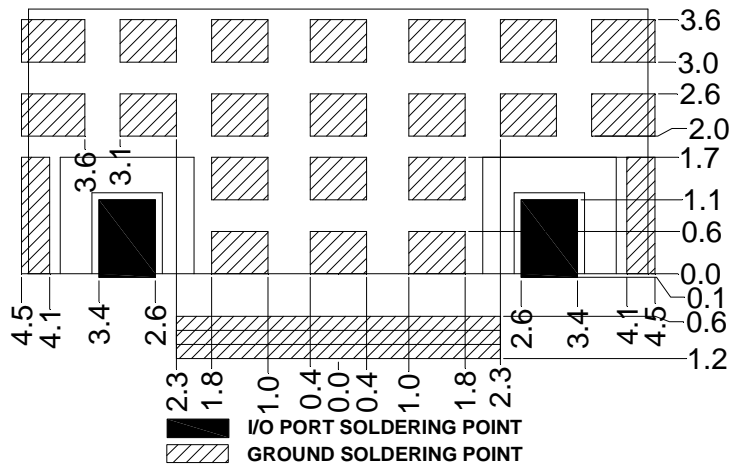
NO.	ITEM	TYP	SPEC	UNIT
1	Center Frequency [fo]		5482.5	MHz
2	Bandwidth [BW]		$f_0 \pm 342.5$ [5150~5835]	MHz
3	Insertion Loss in BW	1.5	2.5 max.@5150~5785 MHz	dB
		2.5	3.0 max.@5785~5835 MHz	
4	Ripple in BW	1.5	2.0 max.@5150~5785 MHz	dB
		1.5	2.0 max.@5785~5835 MHz	
5	Return Loss in BW	13	10 min.@5150~5835 MHz	dB
6	Attenuation[Absolute Value]	/	50 min. @ DC~2500 MHz	dB
		/	40 min. @ 2500~4000 MHz	
		48	45 min. @ 5925~5990 MHz	
		/	50 min. @ 6090~7125 MHz	
		/	50 min. @ 7125~7740 MHz	
		/	30 min. @10360~11610 MHz	
		28	15 min. @ 15540~17415 MHz	

^ All Parameters are measured with 50Ω system at +25°C if not specified.

OUTLINE DRAWING



FOOTPRINT



**ABSOLUTE MAXIMUM RATINGS**

<b>Operation Temperature</b>	-40°C to +100°C
<b>Storage Temperature</b>	-40°C to +85°C
<b>Input Power</b>	1W

**NOTES**

- RoHS 2.0/HSF
- Reflow soldering temperature curve

